

2SK1165, 2SK1166

Silicon N Channel MOS FET

REJ03G0914-0200

(Previous: ADE-208-1252)

Rev.2.00 Sep 07, 2005

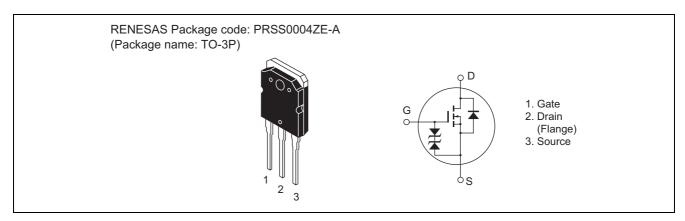
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item		Symbol	Ratings	Unit	
Drain to source voltage	2SK1165	V _{DSS}	450	V	
	2SK1166		500		
Gate to source voltage		V_{GSS}	±30	V	
Drain current		I _D	12	А	
Drain peak current		I _{D(pulse)} *1	48	Α	
Body to drain diode reverse drain current		I _{DR}	12	Α	
Channel dissipation		Pch*2	100	W	
Channel temperature		Tch	150	°C	
Storage temperature		Tstg	-55 to +150	°C	

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at $T_C = 25$ °C

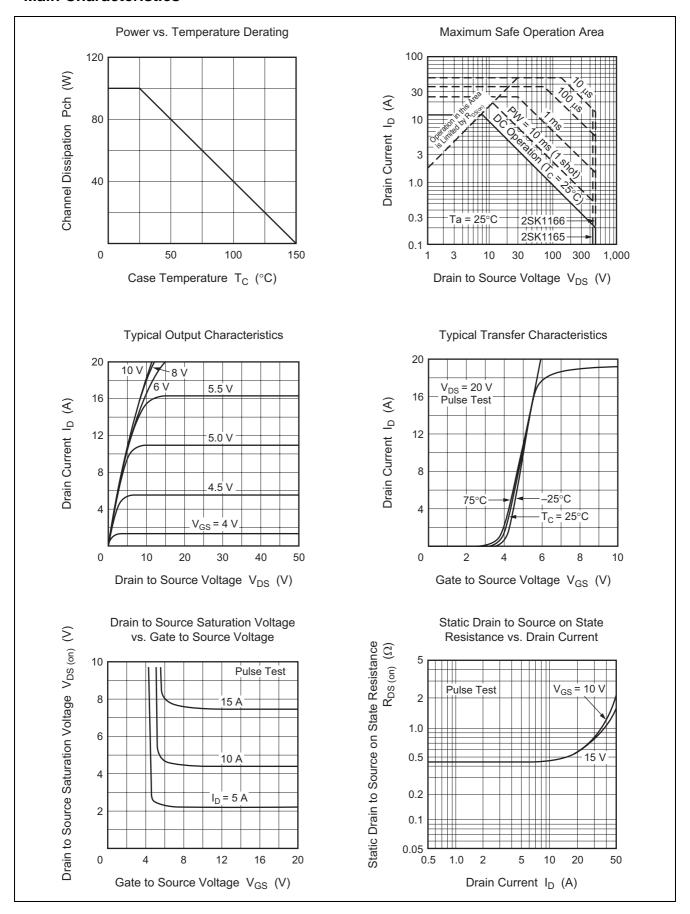
Electrical Characteristics

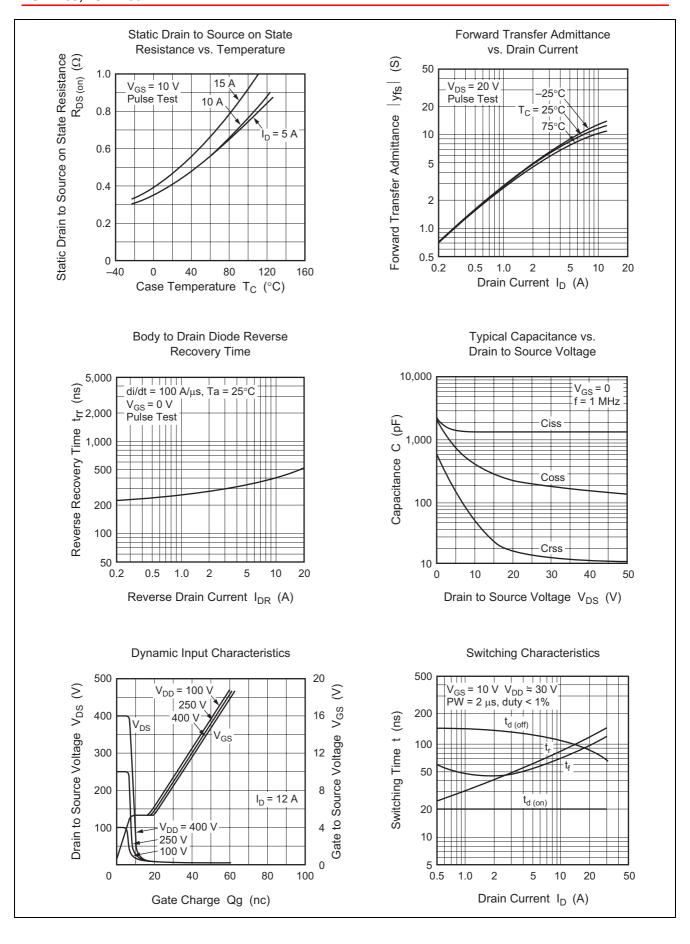
 $(Ta = 25^{\circ}C)$

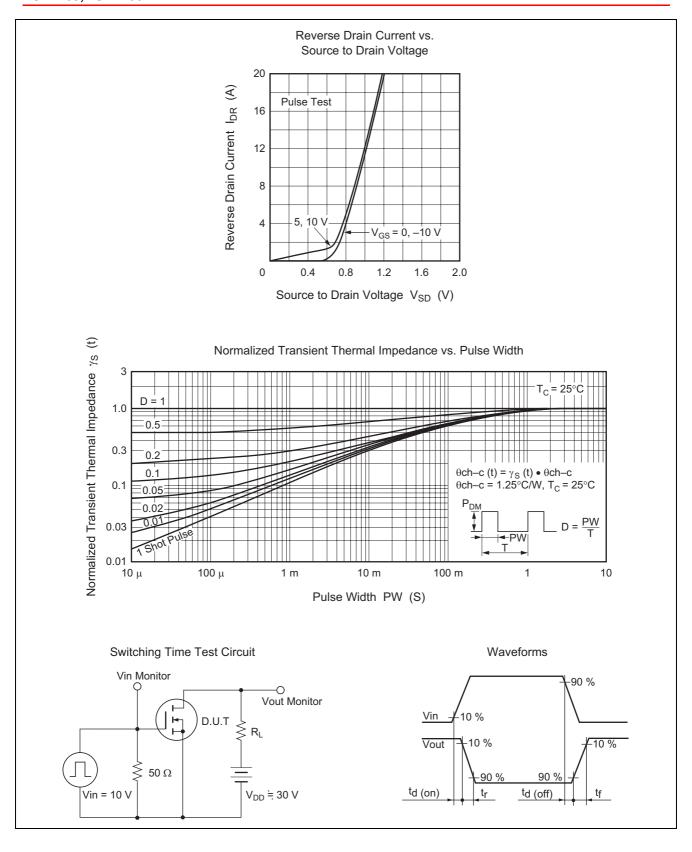
Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SK1165	$V_{(BR)DSS}$	450	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
breakdown voltage	2SK1166		500				
Gate to source breakdown voltage		$V_{(BR)GSS}$	±30	_		V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current		I_{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain	2SK1165	I _{DSS}	_	_	250	μΑ	$V_{DS} = 360 \text{ V}, V_{GS} = 0$
current	2SK1166						$V_{DS} = 400 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage		$V_{GS(off)}$	2.0		3.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on	2SK1165	R _{DS(on)}	_	0.40	0.55	Ω	$I_D = 6 A$, $V_{GS} = 10 V^{*3}$
state resistance	2SK1166		_	0.45	0.60		
Forward transfer admittance		y _{fs}	6.0	10		S	$I_D = 6 A$, $V_{DS} = 10 V^{*3}$
Input capacitance		Ciss	_	1450		pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance		Coss	_	410	_	pF	f = 1 MHz
Reverse transfer capacitance		Crss	_	55		pF	
Turn-on delay time		t _{d(on)}	_	20		ns	$I_D = 6 A, V_{GS} = 10 V,$
Rise time		t _r	_	70		ns	$R_L = 5 \Omega$
Turn-off delay time		$t_{d(off)}$	_	120	_	ns	
Fall time		t _f	_	60	_	ns	
Body to drain diode forward voltage		V_{DF}		1.0	_	V	I _F = 12 A, V _{GS} = 0
Body to drain diode reverse recovery		t _{rr}	_	450	_	ns	$I_F = 12 \text{ A}, V_{GS} = 0,$
time							$di_F/dt = 100 A/\mu s$

Note: 3. Pulse test

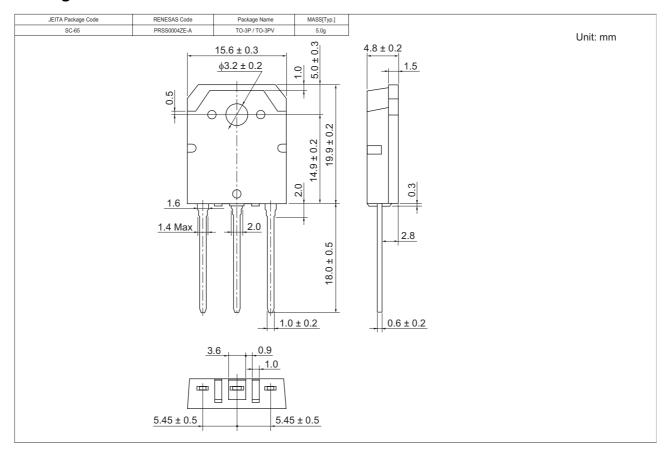
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK1165-E	360 pcs	Box (Tube)
2SK1166-E	360 pcs	Box (Tube)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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